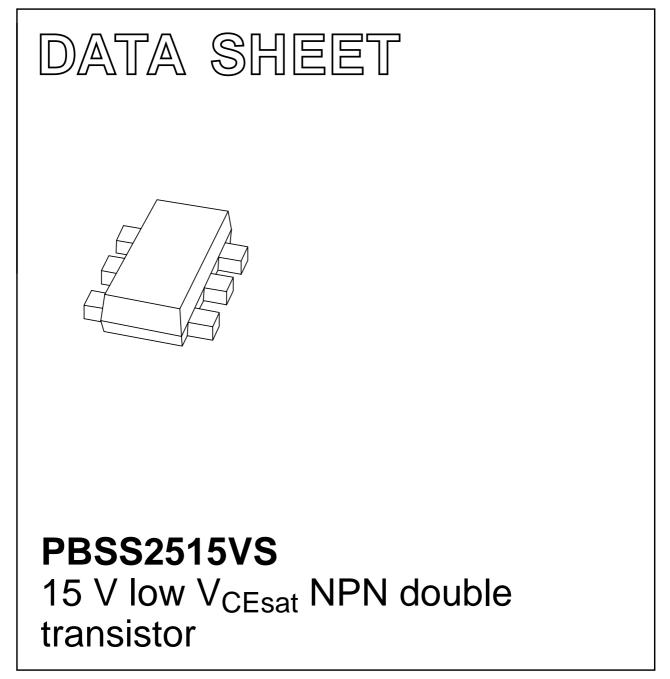
DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 2001 Sep 13

2001 Nov 07



PBSS2515VS

FEATURES

- 300 mW total power dissipation
- Very small 1.6 x 1.2 mm ultra thin package
- Excellent coplanarity due to straight leads
- · Low collector-emitter saturation voltage
- High current capability
- Improved thermal behaviour due to flat lead
- Replaces two SC-75/SC-89 packaged low V_{CEsat} transistors on same PCB area
- Reduces required PCB area
- Reduced pick and place costs.

APPLICATIONS

- · General purpose switching and muting
- Low frequency driver circuits
- LCD backlighting
- Audio frequency general purpose amplifier applications
- Battery driven equipment (mobile phones, video cameras and hand-held devices).

DESCRIPTION

NPN low V_{CEsat} double transistor in a SOT666 plastic package. PNP complement: PBSS3515VS.

MARKING

TYPE NUMBER	MARKING CODE		
PBSS2515VS	N9		

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT	
V _{CEO}	collector-emitter voltage	15	V	
I _{CM}	peak collector current	1	А	
R _{CEsat}	equivalent on-resistance	<500	mΩ	

PINNING

PIN	DESCRIPTION		
1, 4	emitter	TR1; TR2	
2, 5	base	TR1; TR2	
6, 3	collector	TR1; TR2	

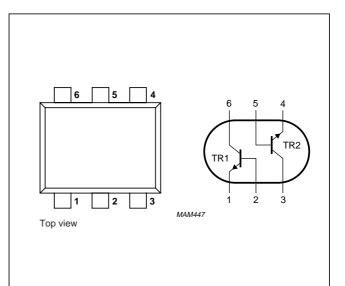


Fig.1 Simplified outline (SOT666) and symbol.

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Per transis	Per transistor unless otherwise specified				
V _{CBO}	collector-base voltage	open emitter	-	15	V
V _{CEO}	collector-emitter voltage	open base	-	15	V
V _{EBO}	emitter-base voltage	open collector	-	6	V
I _C	collector current (DC)		—	500	mA
I _{CM}	peak collector current		-	1	A
I _{BM}	peak base current		-	100	mA
P _{tot}	total power dissipation	$T_{amb} \le 25 \text{ °C}; \text{ note } 1$	-	200	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
T _{amb}	operating ambient temperature		65	+150	°C
Per device) }	•			
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	-	300	mW

Note

1. Transistor mounted on an FR4 printed-circuit board.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT	
R _{th j-a}	thermal resistance from junction to ambient	notes 1 and 2	416	K/W	

Notes

- 1. Transistor mounted on an FR4 printed-circuit board.
- 2. The only recommended soldering method is reflow soldering.

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CHARACTERISTICS

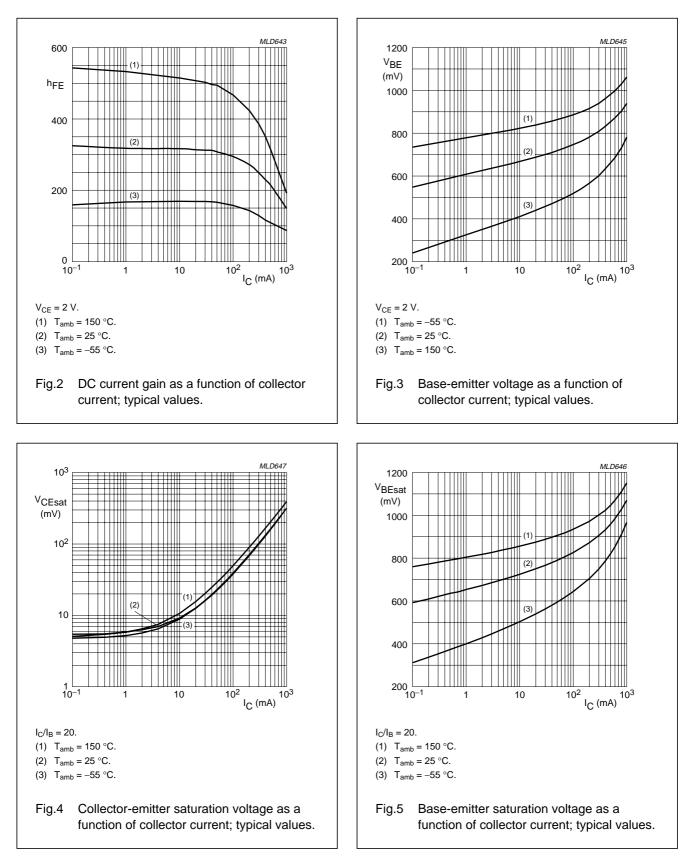
 T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Per transis	Per transistor unless otherwise specified					
I _{CBO}	collector-base cut-off current	$V_{CB} = 15 \text{ V}; \text{ I}_{E} = 0$	-	-	100	nA
		V _{CB} = 15 V; I _E = 0; T _j = 150 °C	-	-	50	μA
I _{EBO}	emitter-base cut-off current	$V_{EB} = 5 \text{ V}; \text{ I}_{C} = 0$	-	-	100	nA
h _{FE}	DC current gain	$V_{CE} = 2 \text{ V}; \text{ I}_{C} = 10 \text{ mA}$	200	-	-	
		V _{CE} = 2 V; I _C = 100 mA; note 1	150	-	-	
		V _{CE} = 2 V; I _C = 500 mA; note 1	90	-	_	
V _{CEsat}	collector-emitter saturation	I _C = 10 mA; I _B = 0.5 mA	-	-	25	mV
	voltage	I _C = 200 mA; I _B = 10 mA	-	-	150	mV
		$I_{C} = 500 \text{ mA}; I_{B} = 50 \text{ mA}; \text{ note } 1$	-	-	250	mV
R _{CEsat}	equivalent on-resistance	$I_{C} = 500 \text{ mA}; I_{B} = 50 \text{ mA}; \text{ note } 1$	-	300	<500	mΩ
V _{BEsat}	base-emitter saturation voltage	$I_{C} = 500 \text{ mA}; I_{B} = 50 \text{ mA}; \text{ note } 1$	-	-	1.1	V
V _{BE}	base-emitter turn-on voltage	V _{CE} = 2 V; I _C = 100 mA; note 1	-	-	0.9	V
f _T	transition frequency	$I_{C} = 100 \text{ mA}; V_{CE} = 5 \text{ V}; \text{ f} = 100 \text{ MHz}$	250	420	_	MHz
C _c	collector capacitance	$V_{CB} = 10 \text{ V}; I_E = I_e = 0; f = 1MHz$	_	4.4	6	pF

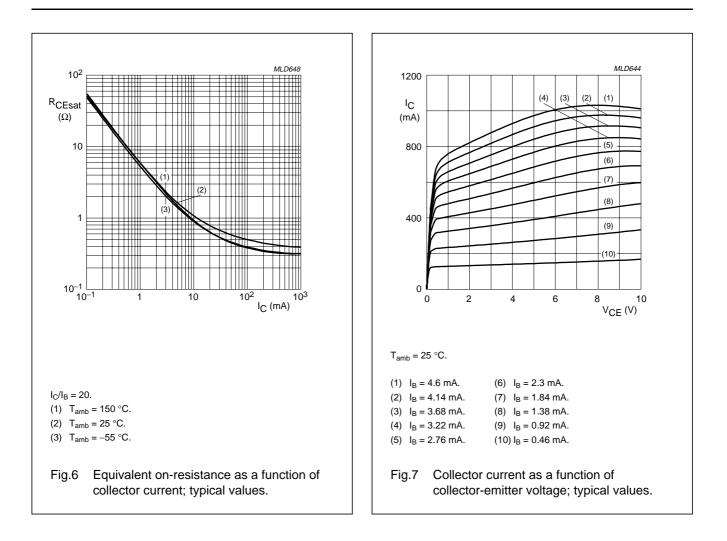
Note

1. Pulse test: $t_p \leq 300 \ \mu s; \ \delta \leq 0.02.$

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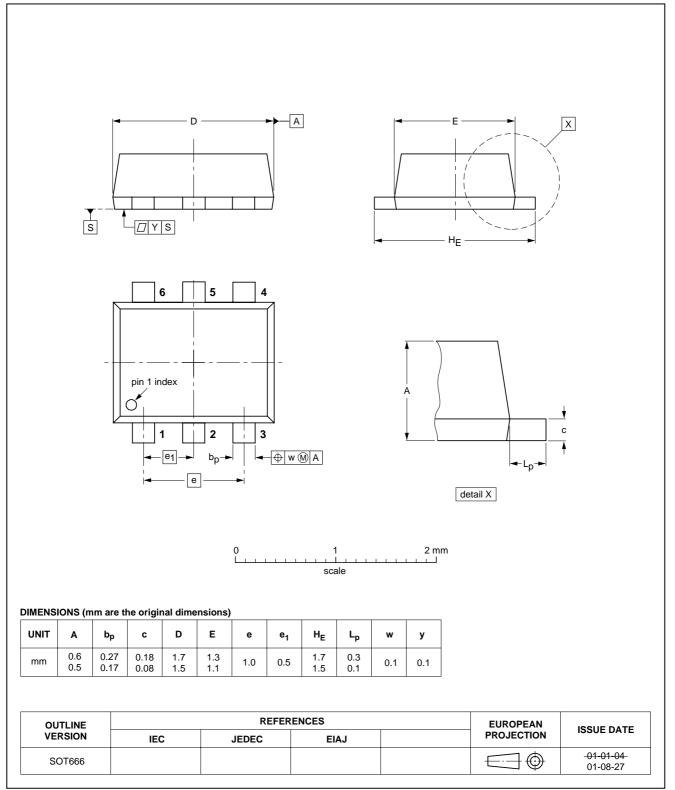


SOT666

15 V low V_{CEsat} NPN double transistor

PACKAGE OUTLINE





PBSS2515VS

DATA SHEET STATUS

DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITIONS
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A.

Notes

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- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

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